

Features:

- Isolated mounting base 4000V~
- Pressure contact technology with Increased power cycling capability
- Space and weight saving

Typical Applications

- Various rectifiers
- DC supply for PWM inverter

V _{DSM} , V _{RSM}	V _{DRM} , V _{RRM}	Type & Outline
2700V	2600V	MDx300-26-415F3
2900V	2800V	MDx300-28-415F3
3100V	3000V	MDx300-30-415F3
3300V	3200V	MDx300-32-415F3
3500V	3400V	MDx300-34-415F3
3700V	3600V	MDx300-36-415F3

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T _j (°C)	VALUE			UNIT
				Min	Type	Max	
I _{F(AV)}	Mean forward current	180° half sine wave 50Hz Single side cooled, T _C =100°C	150			300	A
I _{F(RMS)}	RMS forward current		150			471	A
I _{RRM}	Repetitive peak current	at V _{RRM}	150			35	mA
I _{FSM}	Surge forward current	10ms half sine wave V _R =0.6V _{RRM}	150			7.1	kA
I ² t	I ² t for fusing coordination					252	A ² s*10 ³
V _{FO}	Threshold voltage		150			0.95	V
r _F	Forward slope resistance					0.70	mΩ
V _{FM}	Peak forward voltage	I _{FM} =900A	25			1.85	V
R _{th(j-c)}	Thermal resistance Junction to case	At 180° sine Single side cooled per chip				0.11	°C / W
R _{th(c-h)}	Thermal resistance case to heatsink	At 180° sine Single side cooled per chip				0.04	°C / W
V _{iso}	Isolation voltage	50Hz, R.M.S, t=1min, I _{iso} : 1mA(max)		4000			V
F _m	Terminal connection torque(M10)				12.0		N·m
	Mounting torque(M6)				6.0		N·m
T _{stg}	Stored temperature			-40		125	°C
W _t	Weight				1275		g
Outline	415F3						

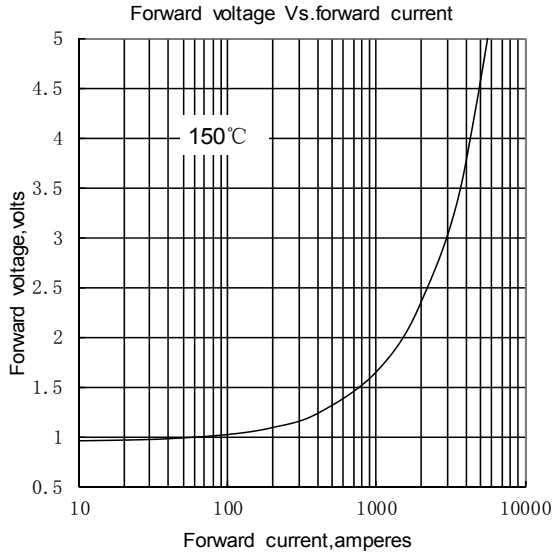


Fig.1

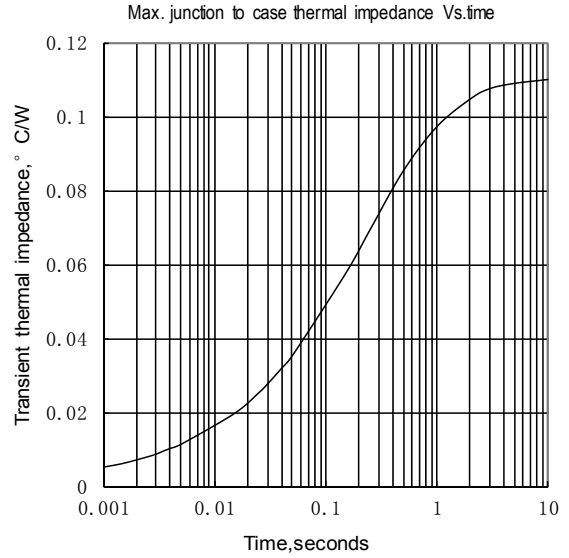


Fig.2

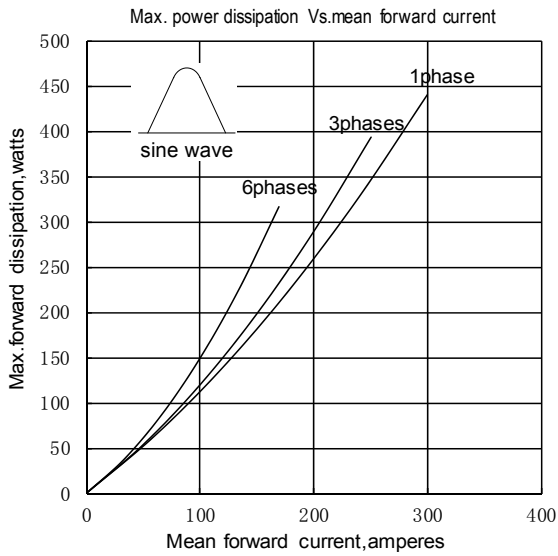


Fig.3

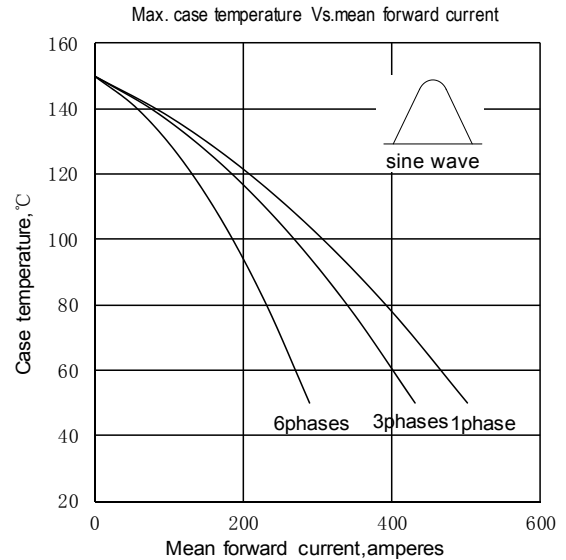


Fig.4

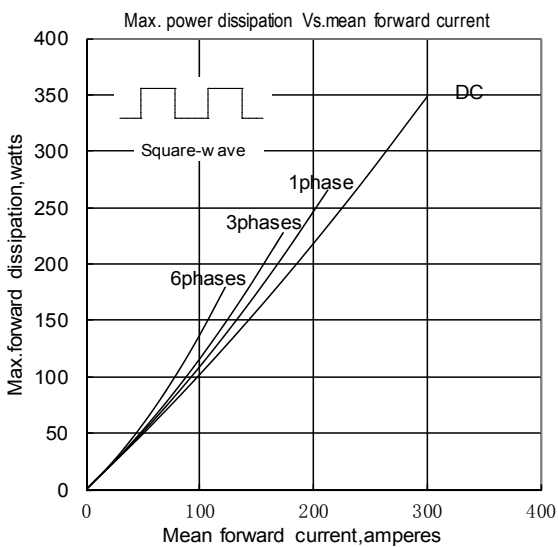


Fig.5

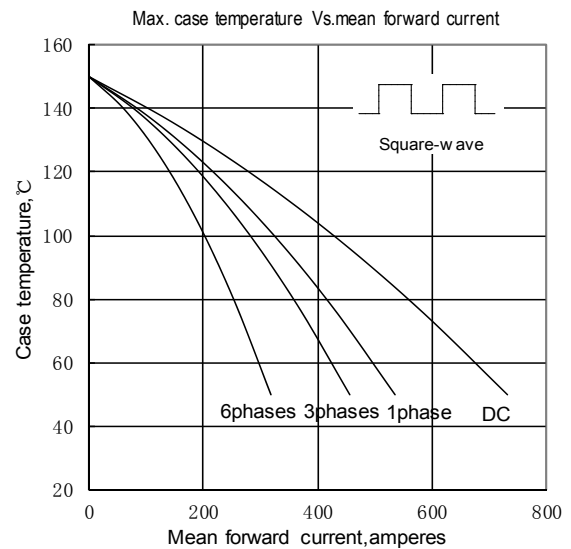


Fig.6

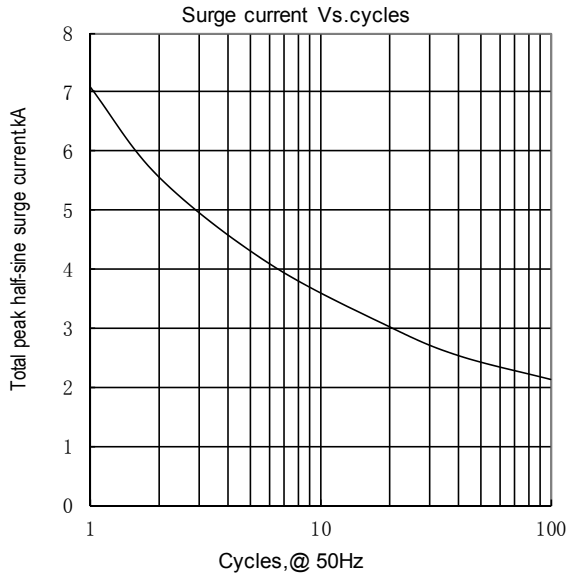


Fig.7

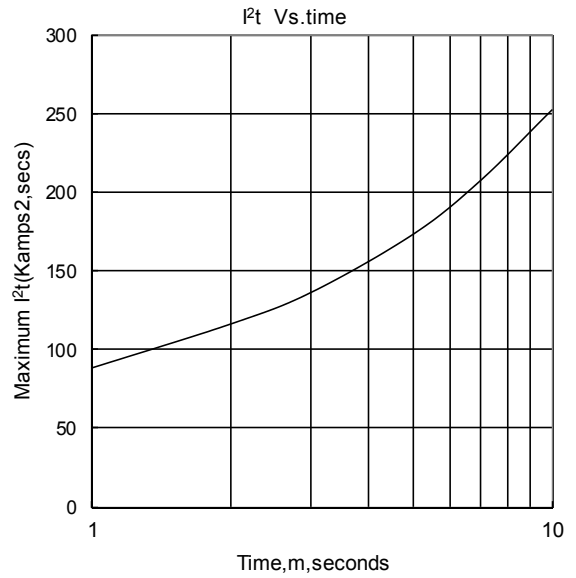


Fig.8

Outline:

